MMVL3401T1G

Silicon Pin Diode

This device is designed primarily for VHF band switching applications but is also suitable for use in general-purpose switching circuits. Supplied in a Surface Mount package.

Features

- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Capacitance: 0.7 pF Typ at $V_R = 20 \text{ Vdc}$
- Very Low Series Resistance at 100 MHz:
 0.34 Ω (Typ) @ I_F = 10 mAdc
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V _R	35	Vdc
Peak Forward Current	Ι _Ε	20	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Total Device Dissipation FR5 Board, T _A = 25°C (Note 1) Derate above 25°C	P _D	200 1.57	mW mW/°C	
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	°C/W	
Junction and Storage Temperature	T _J , T _{stg}	150	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR4 Minimum Pad



ON Semiconductor®

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SILICON PIN SWITCHING DIODE





SOD-323 CASE 477 STYLE 1

MARKING DIAGRAM



4D = Device Code M = Date Code* ■ = Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMVL3401T1G	SOD-323 (Pb-Free)	3000 / Tape & Reel

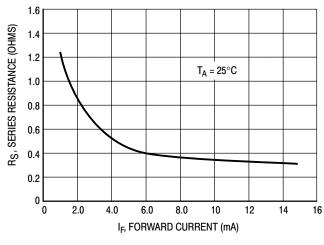
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMVL3401T1G

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μAdc)	V _{(BR)R}	35	_	-	Vdc
Diode Capacitance (V _R = 20 Vdc)	C _T	_	-	1.0	pF
Series Resistance (Figure 5) (I _F = 10 mAdc, f = 100 MHz)	R _S	-	-	0.7	Ω
Reverse Leakage Current (V _R = 25 Vdc)	I _R	-	_	0.1	μAdc

TYPICAL CHARACTERISTICS



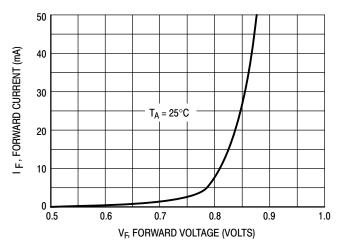


Figure 1. Series Resistance

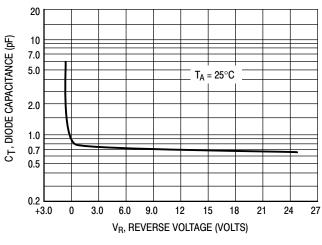


Figure 2. Forward Voltage

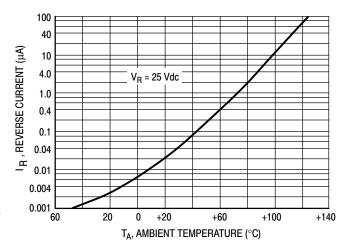


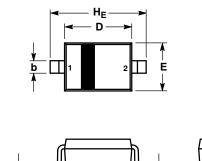
Figure 3. Diode Capacitance

Figure 4. Leakage Current

MMVL3401T1G

PACKAGE DIMENSIONS

SOD-323 CASE 477-02 **ISSUE H**



NOTE 5

NOTE 3



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

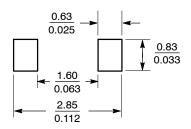
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A 1	0.00	0.05	0.10	0.000	0.002	0.004
А3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
Е	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
He	2.30	2.50	2.70	0.090	0.098	0.105

PIN 1. CATHODE 2. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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